TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

## 2SK2967

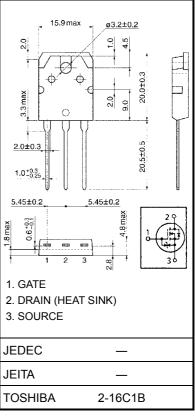
# DC-DC Converter, Relay Drive and Motor Drive Applications

Unit: mm

 $\begin{array}{ll} \bullet & Low\ drain-source\ ON\ resistance & \vdots\ R_{DS}\ (o_N)=48\ m\Omega\ (typ.) \\ \bullet & High\ forward\ transfer\ admittance & \vdots\ |\ Y_{fs}|=30\ S\ (typ.) \\ \bullet & Low\ leakage\ current & \vdots\ I_{DSS}=100\ \mu A\ (max)\ (V_{DS}=250\ V) \\ \bullet & Enhancement-mode & \vdots\ V_{th}=1.5{\sim}3.5\ V\ (V_{DS}=10\ V,\ I_D=1\ mA) \end{array}$ 

#### **Maximum Ratings (Ta = 25°C)**

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	250	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	250	V	
Gate-source voltage		$V_{GSS}$	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	30	Α	
	Pulse (Note 1)	I <sub>DP</sub>	120	Α	
Drain power dissipation	n (Tc = 25°C)	$P_{D}$	150	W	
Single pulse avalanche energy (Note 2)		E <sub>AS</sub>	925	mJ	
Avalanche current		I <sub>AR</sub>	30	Α	
Repetitive avalanche e	nergy (Note 3)	E <sub>AR</sub>	15	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature ra	ange	T <sub>stg</sub>	-55~150	°C	



Weight: 4.6 g (typ.)

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.833	°C/W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	50	°C/W

Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:  $V_{DD}$  = 50 V,  $T_{ch}$  = 25°C (initial), L = 1.74 mH,  $I_{AR}$  = 30 A,  $R_G$  = 25  $\Omega$ 

Note 3: Repetitive rating; Pulse width limited by maximum channel temperature.

This transistor is an electrostatic sensitive device.

Please handle with caution.

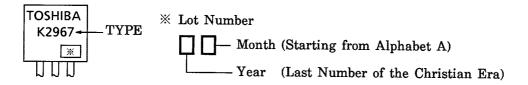
## **Electrical Characteristics (Ta = 25°C)**

Charac	teristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±16 V, V <sub>DS</sub> = 0 V	_	_	±10	μΑ
Drain cut-off cur	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 250 V, V <sub>GS</sub> = 0 V	_	_	100	μΑ
Drain-source brovoltage	eakdown	V <sub>(BR) DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	250	_	_	V
Gate threshold v	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5	_	3.5	V
Drain-source Of	N resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A	_	48	68	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 15 A	15	30	_	S
Input capacitanc	е	C <sub>iss</sub>		_	5400	_	
Reverse transfer	capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	580	_	pF
Output capacitance		Coss	1		1900	_	
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10V}{\circ}_{OV} \stackrel{I_{D}=15A}{\circ}_{V_{OUT}}$ $V_{DD} \stackrel{=}{=} 100V$	_	20	_	
	Turn-on time	t <sub>on</sub>		_	50	_	20
	Fall time	t <sub>f</sub>		_	35	_	ns
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\rm w} = 10 \mu \rm s$	_	200	_	
Total gate charg plus gate-drain)	e (gate-source	Qg			132	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 200 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		80	_	nC -
Gate-drain ("miller") Charge		Q <sub>gd</sub>			52	_	

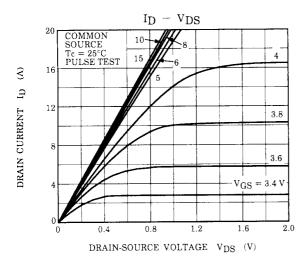
## Source-Drain Ratings and Characteristics (Ta = 25°C)

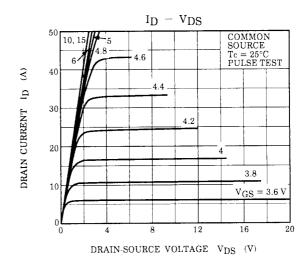
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	_	_	30	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	120	Α
Forward voltage (diode)	V <sub>DSF</sub>	I <sub>DR</sub> = 30 A, V <sub>GS</sub> = 0 V	_	_	-2.0	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 30 A, V <sub>GS</sub> = 0 V	1	270	_	ns
Reverse recovery charge	$Q_{rr}$	dl <sub>DR</sub> / dt = 100 A / μs		3.0	_	μC

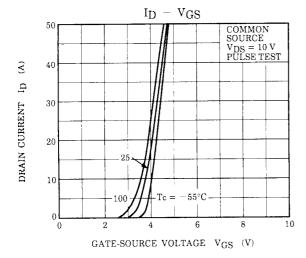
## Marking

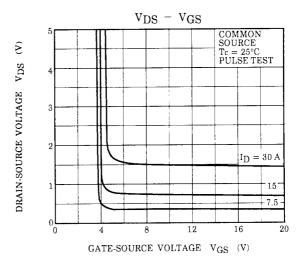


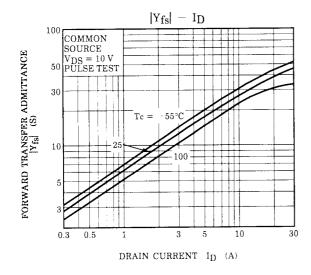
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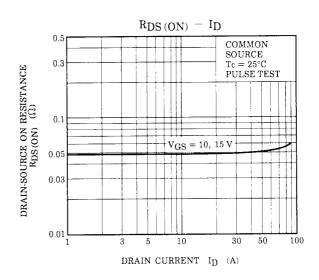


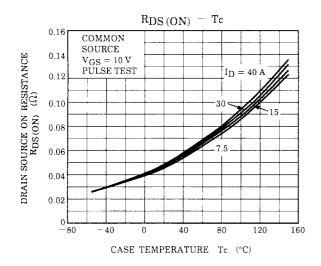


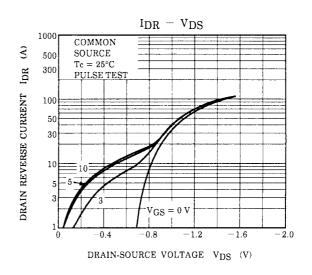


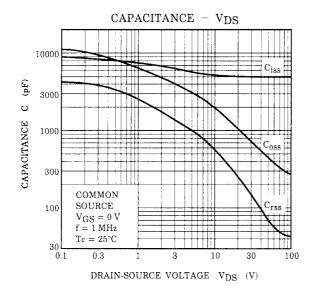


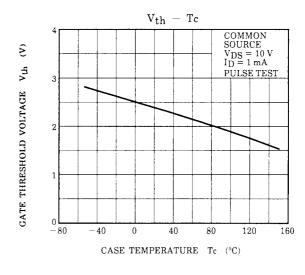


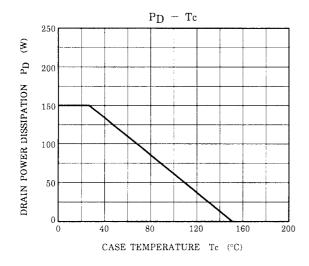


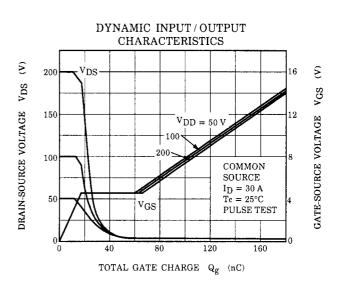




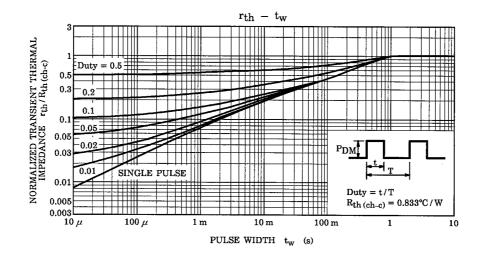


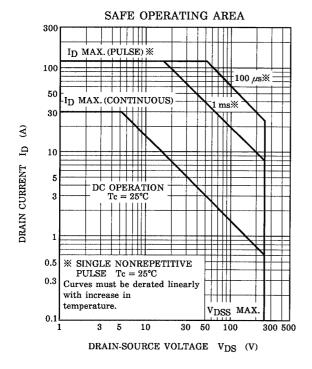


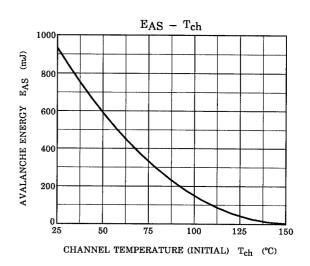


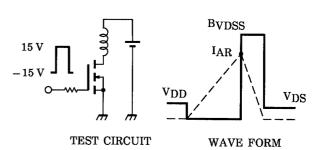


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$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 50~V,~L = 1.74~mH \end{aligned} \quad E_{AS} &= \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right) \end{aligned}$$

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